

General Purpose PNP Epitaxial Planar Transistor

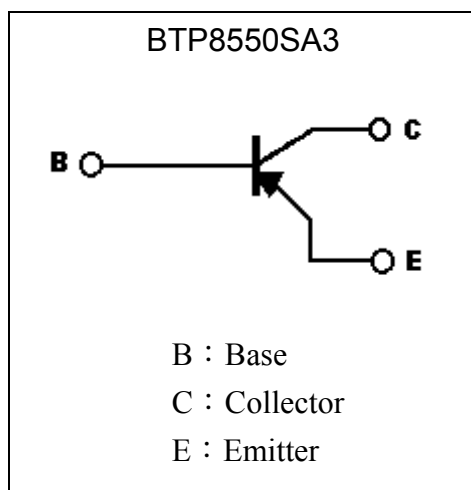
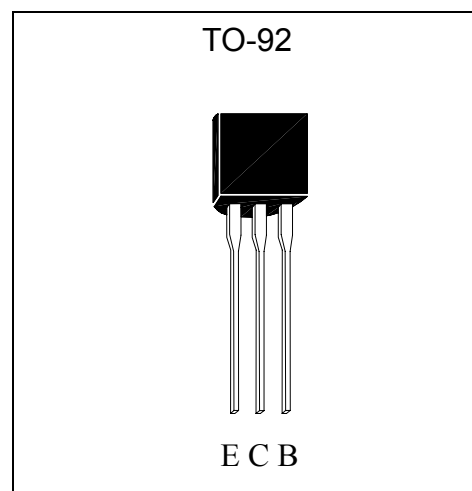
BTP8550SA3

Description

The BTP8550SA3 is designed for use in output amplifier of portable radios in class B push pull operation.

Features

- Large collector current , $I_C = -700\text{mA}$
- Low $V_{CE(sat)}$
- Complementary to BTN8050SA3.

Symbol

Outline

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CB0}	-25	V
Collector-Emitter Voltage	V_{CE0}	-20	V
Emitter-Base Voltage	V_{EB0}	-5	V
Collector Current	I_C	-700	mA
Base Current	I_B	-100	mA
Power Dissipation	P_d	625	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	$^\circ\text{C}/\text{W}$
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55~+150	$^\circ\text{C}$



Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-25	-	-	V	IC=-10μA
BVCEO	-20	-	-	V	IC=-1mA
BVEBO	-5	-	-	V	IE=-10μA
ICBO	-	-	-1	μA	VCB=-20V
*VCE(sat)	-	-	-0.5	V	IC=-500mA, IB=-50mA
*VBE(on)	-	-	-1	V	VCE=-1V, IC=-150mA
*hFE 1	100	-	500	-	VCE=-1V, IC=-150mA
*hFE 2	-	100	-	-	VCE=-1V, IC=-500mA
fT	150	-	-	MHz	VCE=-10V, IC=-20mA, f=100MHz
Cob	-	-	10	pF	VCB=-10V, f=1MHz

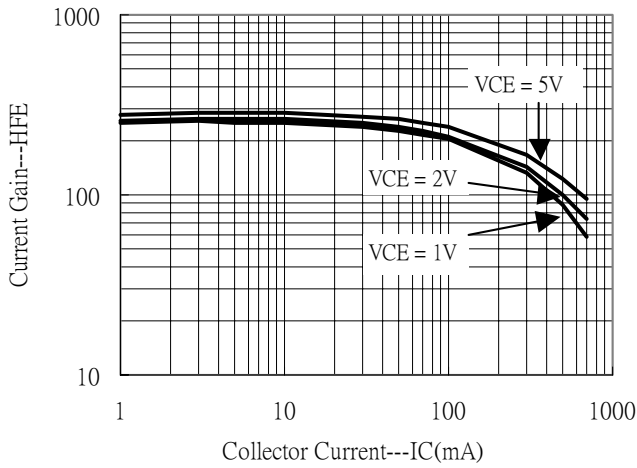
*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Classification Of hFE 1

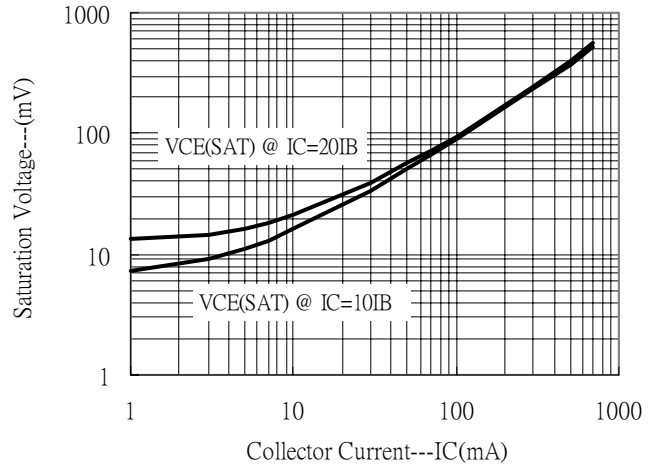
Rank	C	D	E
Range	100~180	160~300	250~500

Characteristic Curves

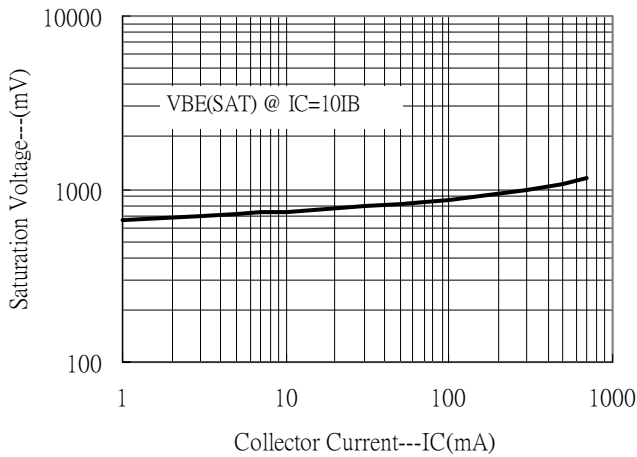
Current Gain vs Collector Current



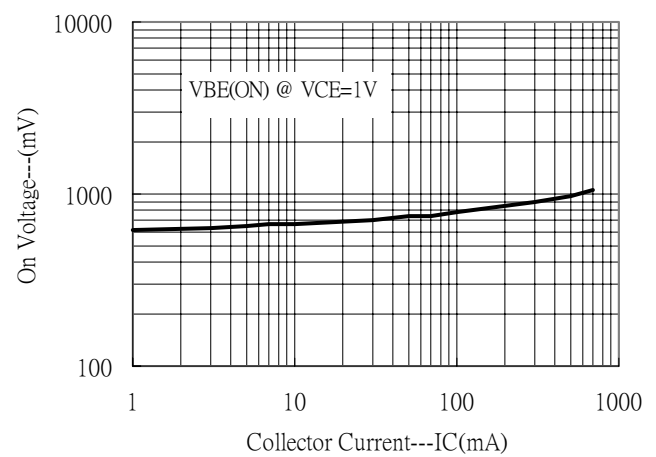
Saturation Voltage vs Collector Current



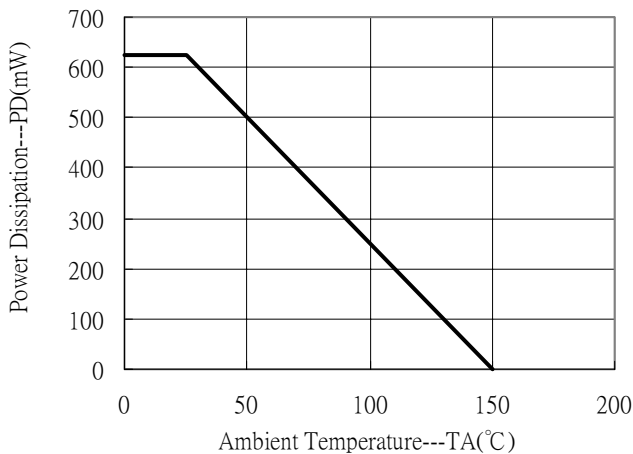
Saturation Voltage vs Collector Current



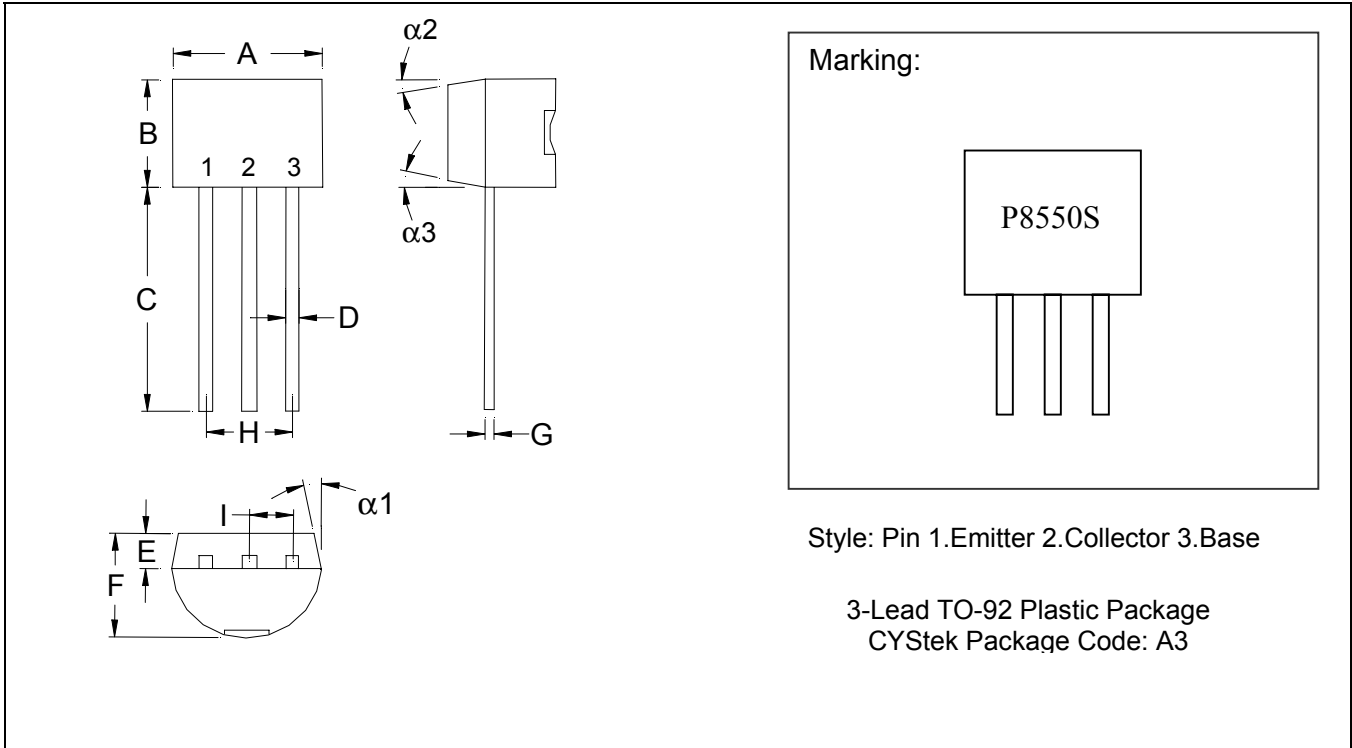
On Voltage vs Collector Current



Power Derating Curve



TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes: 1. Controlling dimension: millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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